

# IEEE Orlando Section Monthly

## Vol. 46, No. 09 - October 2013



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### Section Information

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### IEEE Orlando Section Monthly - Vol. 46, No. 9 - October 2013

#### Section/Society Chapter/Affinity Group Events

- Sep. 27 - IEEE AP/MTT chapter technical meeting
- Oct. 1 - Executive Committee Meeting
- Oct. 1 - CPMT Technical Meeting: 3D IC Packaging and 3D IC integration
- Oct. 3 - AESS Technical Meeting
- Oct. 4 - IEEE AP/MTT chapter technical meeting
- Oct. 16 - Senior Membership Elevation Drive
- Oct. 26 - IEEE Orlando Section 2013 Annual Awards Banquet

#### Section News

- STEAM Rocks! 6th Grade Event Dates: Oct. 4th, Nov. 1st
- Part time STEM Program Assistant
- Volunteers Needed for Senior Membership Elevation Drive
- New Patent Granted to IEEE Orlando Section Member
- Call for Volunteers for Chapter Officers and Committee Officers

#### Report/Newsletters

- IEEE USA 2013 Annual Meeting Highlights: PPTX - PDF
- Region 3 Membership Development Report - June 2013
- IEEE Orlando Section Monthly - October 2013: HTML - PDF

#### Employment Assistance

- [Positions Wanted](#)

#### IEEE Conferences/Annual Meetings/Events

- Oct. 6-11 - IAS Annual Meeting
- June 6 - WAMICON 2014

#### Other IEEE News/Events

- [IEEE-USA IN ACTION New Video: 'Putting the I in IEEE-USA'](#)

#### New Challenges in Electromagnetic Communication: Antenna Design, High-speed Data Transfer and Energy Harvesting

**Host:** IEEE MTT/AP Orlando Chapter

**Speaker:** Prof. Raj Mittra, Penn State University - [Abstract and Biography](#)

**Date:** Friday, September 27, 2013

**Time:** 10:00 - 11:00 AM

**Place:** University of Central Florida HCEC 101

**Cost:** Free to all IEEE members and Non-IEEE members

**Contact:** Kalyan Kamati, [kalyan@knights.ucf.edu](mailto:kalyan@knights.ucf.edu), tel. (407)569-6898

**Website:** [www.ieee.org/orlando](http://www.ieee.org/orlando)

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#### IEEE Orlando Section Executive Committee Meeting

**Date:** Tuesday, October 1, 2013

**Time:** 6:30 - 7:00 pm - Social and Refreshments; 7:00 - 9:00 pm Executive Committee Meeting

**Place:** Orlando Business Development Center, District 2 (affiliated with the UCF and the S.B.A.) at 3218 East Colonial Drive, Suite #G, Orlando, FL 32802

**Directions:** In Herndon Plaza just east of Maguire Blvd. This is the shopping center across Colonial Drive from Fashion Square. It is on the west end of the building, around the building at the Southwest corner from the HH Gregg entrance.

**Cost:** Free to all IEEE members and Non-IEEE members

**RSVP:** [mcorlovsky@ieee.org](mailto:mcorlovsky@ieee.org)

**Contact:** Mike Orlovsky, [mcorlovsky@ieee.org](mailto:mcorlovsky@ieee.org), tel. 410.979.0476 (Cell)

**Website:** [www.ieee.org/orlando](http://www.ieee.org/orlando)

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### **CPMT Technical Meeting: 3D IC Packaging and 3D IC integration**

**Speaker:** John Lau, an ASME and IEEE Fellow since 1994, will present a presentation and technical talk on 3D IC Packaging and 3D IC integration. John H. Lau has been an ITRI (Industrial Technology Research Institute) Fellow in Taiwan since January 2010. Prior to that, he was with HPL/Agilent in California, US for more than 25 years.

**Abstract:** 3D IC packaging and 3D IC integration are different. In general, the TSV (through-silicon via) separates 3D IC packaging from 3D IC integration because the latter use TSVs, but 3D IC packaging does not. TSV is the heart and most important key enabling technology of 3D IC integration. It provides the opportunity for the shortest chip-to-chip, and the smallest pad size and pitch of interconnects. The potential applications of 3D IC integration are: (1) memory-chip stacking, (2) wide I/O memory (or logic-on-logic), (3) wide I/O DRAM (or hybrid memory cube), and (4) wide I/O interface. In this presentation, the technology supply chains and the critical steps such as FEOL (front-end-of-line), MOL (middle-of-line), BEOL (back-end-of-line), TSV, MEOL (middle-end-of-line), assembly, and test and their ownerships for high-volume manufacturing for those 4 groups of 3D IC integration will be discussed. The 3D IC packaging, which has been keeping 3D IC integration away from volume production, will be briefly mentioned first.

**Date:** Tuesday, October 01, 2013

**Time:** 8:00 PM (Immediately after Section EXCOM Meeting)

**Place:** Orlando Business Development Center, District 2 (affiliated with the UCF and the S.B.A.) at 3218 East Colonial Drive, Suite #G, Orlando, FL 32802

**Directions:** In Herndon Plaza just east of Maguire Blvd. This is the shopping center across Colonial Drive from Fashion Square. It is on the west end of the building, around the building at the Southwest corner from the HH Gregg entrance.

**Cost:** Free to all IEEE members and Non-IEEE members

**Contact:** Scott Clary, [scott.a.clary@lmco.com](mailto:scott.a.clary@lmco.com)

**Website:** [www.ieee.org/orlando](http://www.ieee.org/orlando)

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### **AESS Technical Talk: Aircraft Avionics Equipage for FAA NextGen Flight Control System**

**Presenter:** Ron T. Ogan, IEEE Senior Member IEEE Aerospace & Electronic Systems Society Board of Governors

**Abstract:** The Federal Aviation Administration (FAA) has authorized transformation of the United States Air Traffic Control System from a radar based technology to a system utilizing Global Positioning System (GPS) Technology over the time period 2013-2020 which will require all aircraft, commercial and general aviation, operating in controlled airspace to be in compliance on January 1, 2020. Current requirements for Automatic Dependent Surveillance – Broadcast (ADS-B) In are stated in AC 20-165, TSO-C154c and TSO-C166b. Aircraft transponders will be upgraded from Mode-C, radar based, to Mode-S, GPS based which will provide precise position, altitude, velocity, and flight direction. Aircraft equipped with ADS-B receivers and multi-function displays (referred to as "glass cockpit" equipment) will connect to ground stations to provide current weather and aircraft traffic graphically displayed for increased safety. The FAA Next Generation Air Transportation System is a transformative change in the management and operation of how we fly. NextGen enhances safety, reduces delays, saves fuel and reduces aviation's adverse environmental impact.

**Date:** Thursday, October 3, 2013

**Time:** 6:30 - 7:00 pm - Social and Refreshments; 7:15 - 9:00 pm Presentation and Discussion

**Place:** Orlando Business Development Center, District 2 (affiliated with the UCF and the S.B.A.) at 3218 East Colonial Drive, Suite #G, Orlando, FL 32802

**Directions:** In Herndon Plaza just east of Maguire Blvd. This is the shopping center across Colonial Drive from Fashion Square. It is on the west end of the building, around the building at the Southwest corner from the HH Gregg entrance.

**Cost:** Free to all IEEE members and Non-IEEE members

**RSVP:** [mcorlovsky@ieee.org](mailto:mcorlovsky@ieee.org)

**Contact:** Mike Orlovsky, [mcorlovsky@ieee.org](mailto:mcorlovsky@ieee.org), tel. 410.979.0476 (Cell)

**Website:** [www.ieee.org/orlando](http://www.ieee.org/orlando)

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### **Design, Analysis, and Applications of Waveguide-Fed Slot Arrays**

**Host:** IEEE MTT/AP Orlando Chapter

**Speaker:** Prof. Sembiam Rengarajan, California State University, Northridge - [Abstract and Biography](#)

**Date:** Friday, October 4, 2013

**Time:** 5:00 - 6:00 PM

**Place:** University of Central Florida HCEC 101

**Cost:** Free to all IEEE members and Non-IEEE members

**Contact:** Kalyan Kamati, [kalyan@knights.ucf.edu](mailto:kalyan@knights.ucf.edu) , tel. (407)569-6898

**Website:** [www.ieee.org/orlando](http://www.ieee.org/orlando)

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### Senior Membership Elevation Drive

**Date:** Wednesday, October 16, 2013

**Time:** 5:30 - 7:00 pm

**Place:** Nova Southeastern University - Orlando Student Educational Center, Room 300, 4850 Millennia Blvd., Orlando, FL 32839

Are you an IEEE member with at least 10 years of professional practice and at least five years of significant performance, and haven't applied for Senior Member elevation? Come join us at the IEEE Orlando Section Senior Membership Drive to learn about the Senior Member benefits and to start the elevation process. Please bring your IEEE membership number as well as a copies of your CV so that we can help elevate you to senior member.

**Contact:** For more information, contact Joe Juisai at +1 415 260-1980 (Cell) or [Joe.Juisai@IEEE.org](mailto:Joe.Juisai@IEEE.org)

**Website:** [www.ieee.org/orlando](http://www.ieee.org/orlando)

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### VOLUNTEERS NEEDED

The IEEE Senior Membership Elevation Drive seeks volunteers to assist with the senior membership elevation drive on Wednesday 16 October 2013. Those who are senior members or higher can assist with elevation recommendations, while those who are not can assist with logistics.

For more information, contact Joe Juisai at +1 415 260-1980 (Cell) or [Joe.Juisai@IEEE.org](mailto:Joe.Juisai@IEEE.org)

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### IEEE Orlando Section 2013 Annual Awards Banquet

**Speaker:** Dr. Roger Smith, PhD, DM, MBA, MS (Cert: PMP, CMSP) Chief Technology Officer, Florida Hospital, Nicholson Center for Surgical Advancement Graduate Faculty Scholar, Modeling and Simulation Program, University of Central Florida Professor of Mathematics and Statistics, Adventist University of Health Sciences

**Topic:** Robotic Surgical System.

**Date:** Saturday, October 26th, 2013

**Time:** Starting at 6:00 pm with dinner being served at 7:00 p.m. with meeting and awards immediately after. Appetizers and beverages will be served from 6:00 p.m. till 7:00 p.m. A Cash bar will also be available.

**Place:** The venue will be the [Renaissance Inn](#) (the *Normandie* Suite) at 5445 Forbes Place (1/2 mile north of the airport, just off Hwy 436 or Semoran), Orlando, Florida, 32812. All participants will receive free parking.

**Cost:** The fees for attendance will be as follows:

	If Purchased By 10/01/2013	After 10/01/2013
IEEE Member and Guest	\$25.00/person	\$35.00/person
IEEE Student Member and Guest	\$15.00/person	\$25.00/person
IEEE Life Member and Guest	\$15.00/person	\$25.00/person
Awards Winner and Guest	Free	Free
Student Scholarship Winner	Free	Free
Others	\$40.00/person	\$50.00/person

**RSVP:** Deadline for all reservations is C.O.B. October 21, 2013. Please confirm your intent to attend, along with your desired main course (Chicken, London Broil or vegetarian) to: [stanbuchanan@IEEE.org](mailto:stanbuchanan@IEEE.org) or [lynguthre@aol.com](mailto:lynguthre@aol.com).

**Menu:** The menu will include Fresh Greens, starch, desert and vegetable and main course choice of Grilled Chicken or London Broil (vegetarian plates are available on request).

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### MEMBER RECOGNITION: New Patent Granted to IEEE Orlando Section Member

Dr. Michael Hassan. IEEE Orlando Section PACE and Consultant Network Chair, was granted a new patent titled "Digital Communication Method and System" on Aug. 18, 2013.

The Orlando Section Monthly seeks member achievements: If an IEEE colleague received an award, promotion, appointment, or any other achievement, please inform The Orlando Section Monthly so it can run a notice in its monthly Member Recognition column. In addition to providing the member's name and membership number, please include a brief biography of the member's career and a description of the achievement. Send all notices to [orlando@ieee.org](mailto:orlando@ieee.org)

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### STEAM Rocks! 6th Grade Event Dates

These 2 STEAM (science-technology-engineering-art-math) Rocks! 6th Grade event dates are official! Our target audience will be 6th graders involved in the Boys & Girls Clubs of Central Florida After School Zone.

Simply show up at the appointed time...you will be handed a T-shirt to pop on so that students may easily identify you as one of our "STEAM Rocks!" volunteers. We will be providing students with the hands on activities. All that you will need to bring is a willingness to help out, a positive attitude, and a smile!

Friday, October 4th, 4 PM to 6 PM  
 Robinswood Middle School  
 6305 Balboa Drive, Orlando, FL 32818  
 Contact on site: Jennifer Grow and Saceta Valentine

Friday, November 1st, 4 PM to 6 PM  
 Corner Lake Middle School  
 1700 Chuluota Road, Orlando, FL 32820  
 Contact on site: Shannon Kassim and Suzanne Lawe

Register at the link below: <https://docs.google.com/spreadsheet/viewform?fromEmail=true&formkey=dDhuWmFnZmp3WXdTQXdMRG5zbF96Znc6MQ>

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### Part time STEM Program Assistant

A great opportunity for our IEEE members to powerfully give back to our community and if you wear your IEEE T-shirt while there, you will help us to better market IEEE around the Central Florida area!

Part time STEM Program Assistant for the Boys & Girls Clubs After School Zone :

<http://www.bgccf.org/wp-content/uploads/2013/08/program-assistant-stem.pdf>

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### IEEE Orlando Section Calendar

#### IEEE Orlando Section Calendar

Today | **September 2013** ▼ Print Week Month Agenda ▾

Sun	Mon	Tue	Wed	Thu	Fri	Sat
Sep 1	2	3 EXCOM Mtg	4	5	6	7
8	9	10	11	12	13	14
15 PES/PELS/IAS	16	17	18	19	20	21
22	23	24	25	26	27 MTT/AP Mtg	28
29	30 6:30pm ExCom Mtg 8pm CPMT Mtg	Oct 1	2	3 AESS Technical	4 MTT/AP Mtg	5

Events shown in time zone: Eastern Time

Last Update: September 23, 2013

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